Tool ID: 144 Tool Location: 107

#### **Equipment Information Sheet**

# Plasma-Therm Takachi HDP-CVD

Manager:Jeremy Clark607-254-6487Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

## **SAFETY**

• User must remain in the lab during tool operation

# **USAGE RESTRICTIONS**

- Do not modify recipes without prior staff approval
- Run "Clean with Endpoint" after running any depositions

## **SCHEDULING/SIGN-UP RESTRICTIONS**

• 3 hour block reservation limit from 8AM - 6PM during weekdays

Minimum Tool Time: 15

minutes

# **MATERIALS COMPATIBILITY CATEGORY**

Tool Category 3: Silcion, III-V Compound Semiconductor, Glass and Metal Category	
Allowed	Not Allowed
Tool category 1/1E and 2 materials	Glass Substrates
III/V compound Semiconductors allowed	No CNF Class A or Class B metals-and oxides/compounds of i.e. (Magnesium,Zinc, Barium, Calcium)
PECVD and ALD Films	No High Vapor pressure materials
Cured organics and baked Photoresist	
Organic/Bio Materials prepped w/o Salt Buffers	

High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.

## **Additional Material Restrictions and Exceptions**

- If any polymer is present on wafer, 5mm of the edge must be removed
- Polymers must be fully cured at least 25C hotter than the deposition temperature
- No metals should be exposed to the plasma without staff approval

Last Updated: 10/12/2021